



ALPHA & OMEGA
SEMICONDUCTOR

AONS66415
40V N-Channel AlphaSGT™

General Description

- AlphaSGT™ N-Channel Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Enhance body diode performance
- RoHS 2.0 and Halogen-Free Compliant

Applications

- DC Motor Drive and BMS industrial application
- Synchronous Rectification in DC/DC and AC/DC Converters

Product Summary

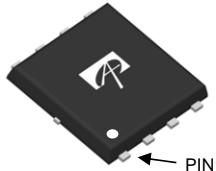
V_{DS}	40V
I_D (at $V_{GS}=10V$)	150A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 2.9mΩ
$R_{DS(ON)}$ (at $V_{GS}=8V$)	< 3.3mΩ

100% UIS Tested
100% R_g Tested

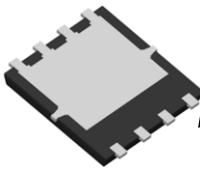


DFN5x6

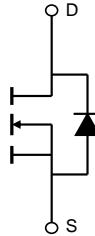
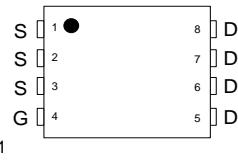
Top View



Bottom View



Top View



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AONS66415	DFN 5x6	Tape & Reel	3000

Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	150	A
$T_C=100^\circ C$		98	
Pulsed Drain Current ^C	I_{DM}	240	
Continuous Drain Current	I_{DSM}	35	A
$T_A=70^\circ C$		28	
Avalanche Current ^C	I_{AS}	45	A
Avalanche energy $L=0.1\text{mH}$ ^C	E_{AS}	101	mJ
Power Dissipation ^B	P_D	131	W
$T_C=100^\circ C$		50	
Power Dissipation ^A	P_{DSM}	6.2	W
$T_A=70^\circ C$		4	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A $t \leq 10s$	$R_{θJA}$	15	20	°C/W
Maximum Junction-to-Ambient ^{A,D} Steady-State		40	50	°C/W
Maximum Junction-to-Case	$R_{θJC}$	0.74	0.95	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=100\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2.4	3	3.6	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=20\text{A}$		2.4	2.9	$\text{m}\Omega$
		$V_{GS}=8\text{V}, I_D=20\text{A}$ $T_J=125^\circ\text{C}$		3.9	4.8	
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=20\text{A}$		77		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.7	1	V
I_S	Maximum Body-Diode Continuous Current				60	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=20\text{V}, f=1\text{MHz}$		3030		pF
C_{oss}	Output Capacitance			515		pF
C_{rss}	Reverse Transfer Capacitance			37		pF
R_g	Gate resistance	$f=1\text{MHz}$	0.2	0.5	1	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=20\text{V}, I_D=20\text{A}$		34	48	nC
Q_{gs}	Gate Source Charge			10		nC
Q_{gd}	Gate Drain Charge			3.4		nC
Q_{oss}	Output Charge	$V_{GS}=0\text{V}, V_{DS}=20\text{V}$		21		nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=10\text{V}, V_{DS}=20\text{V}, R_L=1\Omega,$ $R_{\text{GEN}}=3\Omega$		11.5		ns
t_r	Turn-On Rise Time			2.5		ns
$t_{\text{D(off)}}$	Turn-Off Delay Time			29		ns
t_f	Turn-Off Fall Time			2.5		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=20\text{A}, di/dt=500\text{A}/\mu\text{s}$		17		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=20\text{A}, di/dt=500\text{A}/\mu\text{s}$		55		nC

A. The value of R_{vJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The Power dissipation P_{DSM} is based on $R_{\text{vJA}} \leq 10\text{s}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(\text{MAX})}=150^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$.

D. The R_{vJA} is the sum of the thermal impedance from junction to case R_{vJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using $<300\mu\text{s}$ pulses, duty cycle 0.5% max.

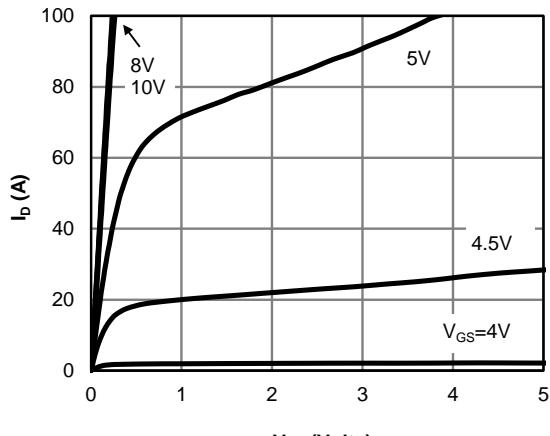
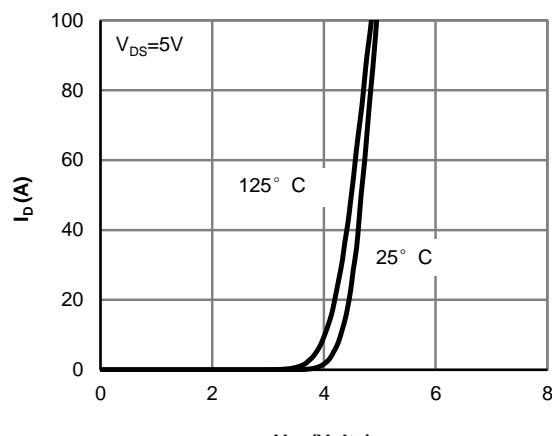
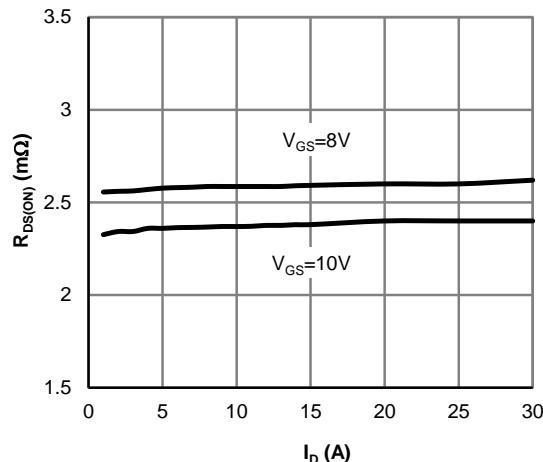
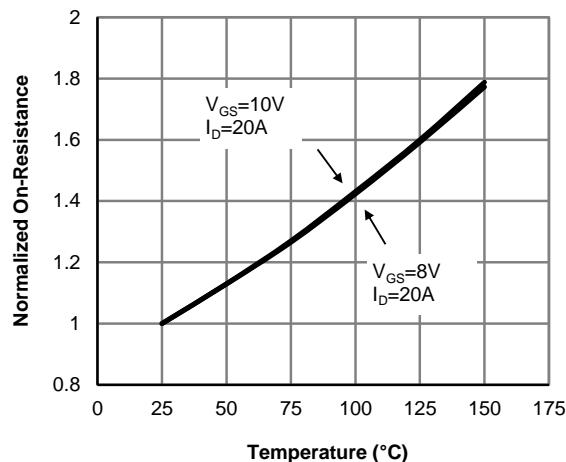
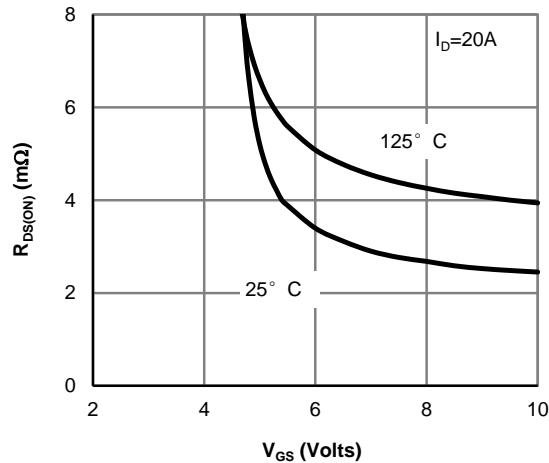
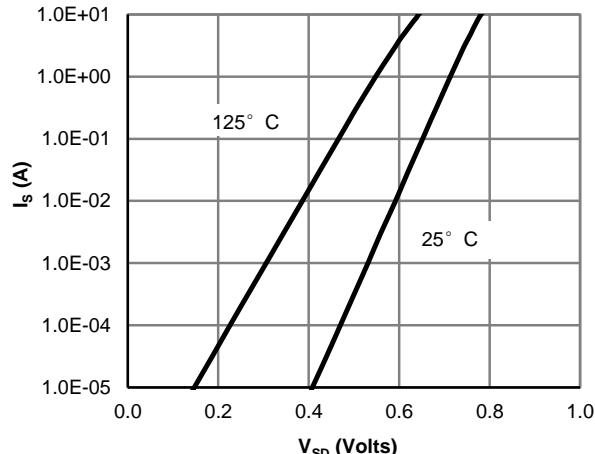
F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(\text{MAX})}=150^\circ\text{C}$. The SOA curve provides a single pulse rating.

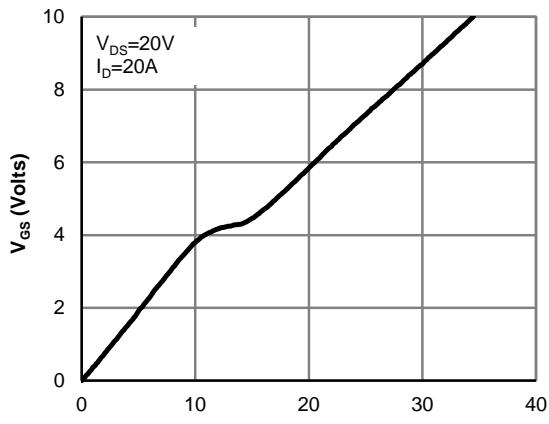
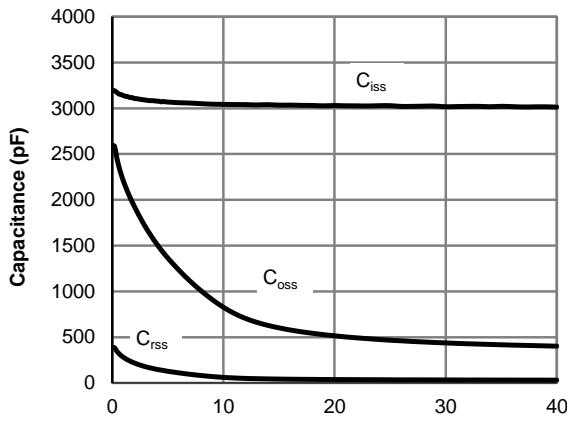
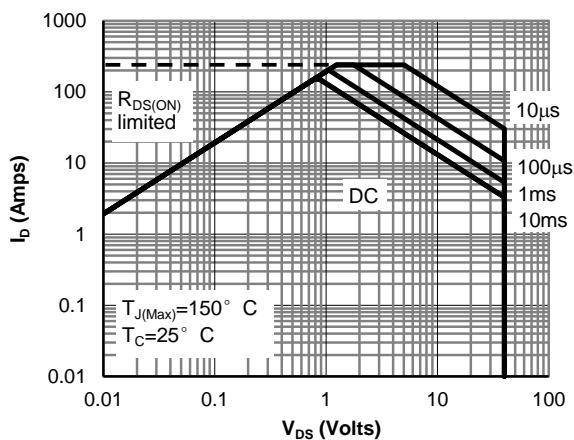
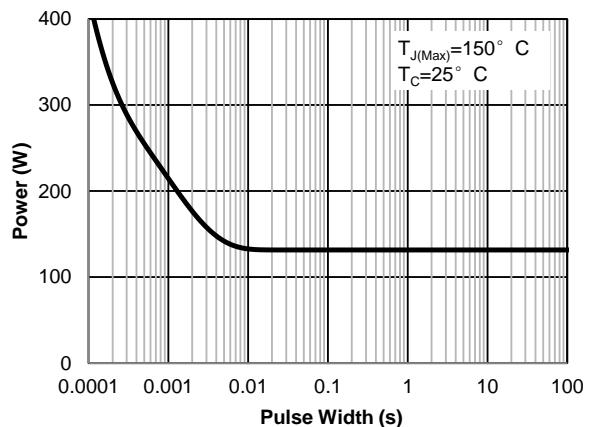
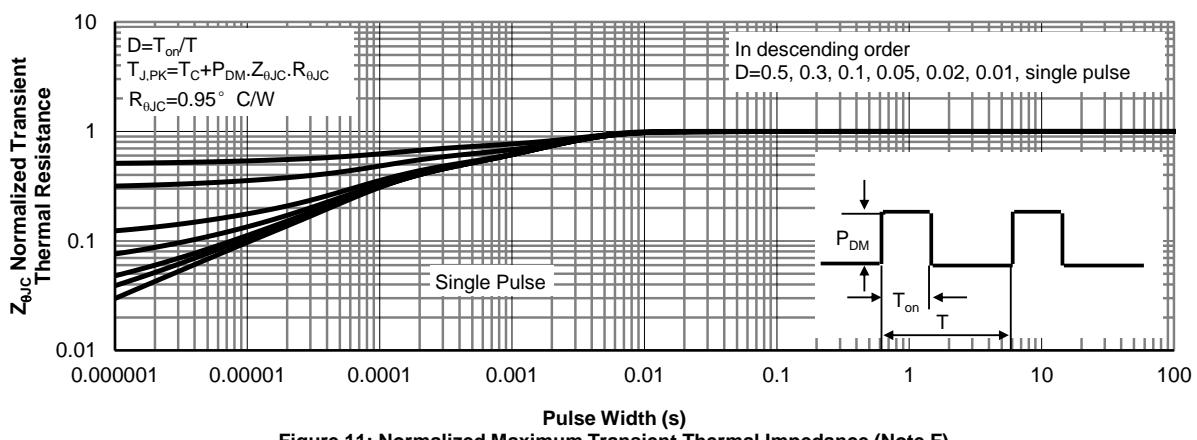
G. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1: On-Region Characteristics (Note E)

Figure 2: Transfer Characteristics (Note E)

Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

Figure 4: On-Resistance vs. Junction Temperature (Note E)

Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7: Gate-Charge Characteristics

Figure 8: Capacitance Characteristics

Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

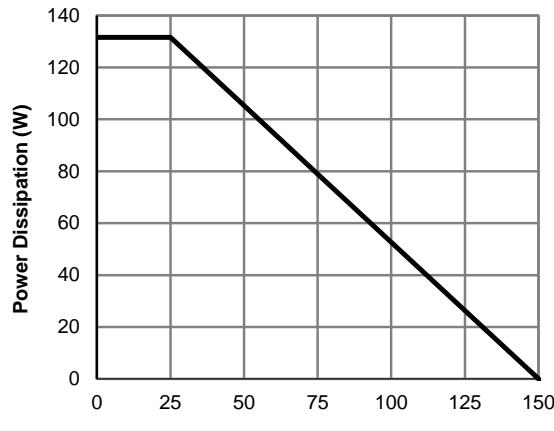
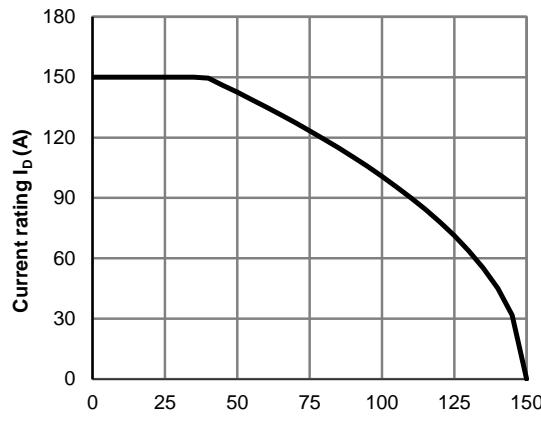
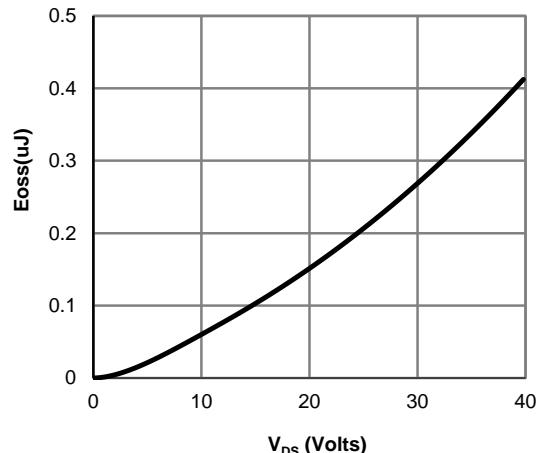
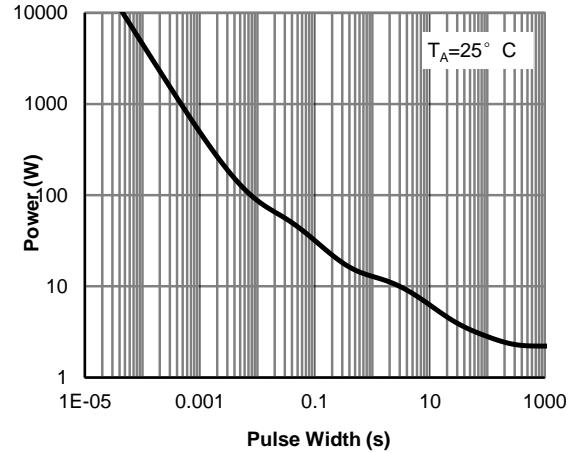
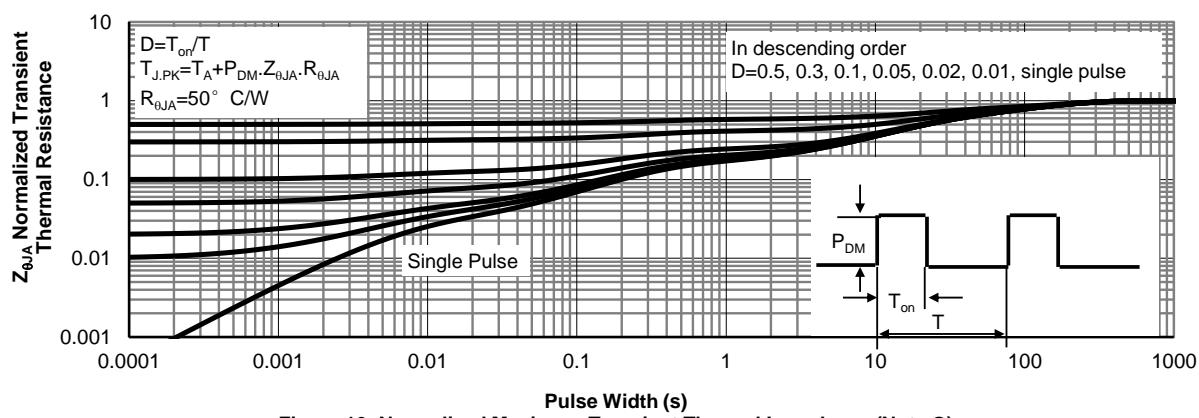
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 12: Power De-rating (Note F)

Figure 13: Current De-rating (Note F)

Figure 14: Coss stored Energy

**Figure 15: Single Pulse Power Rating
Junction-to-Ambient (Note G)**

Figure 16: Normalized Maximum Transient Thermal Impedance (Note G)

Figure A: Gate Charge Test Circuit & Waveforms

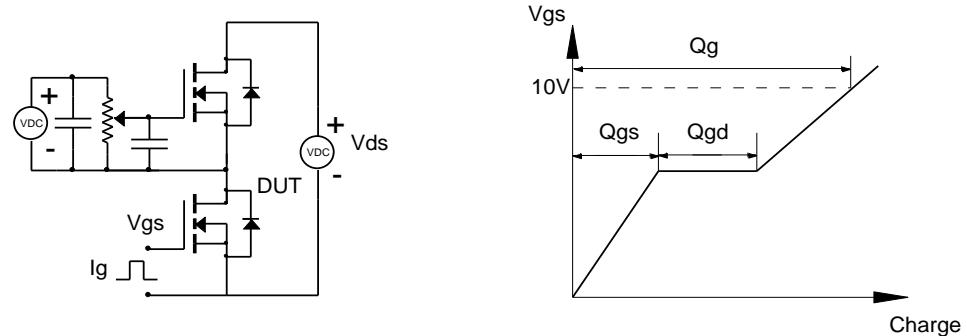


Figure B: Resistive Switching Test Circuit & Waveforms

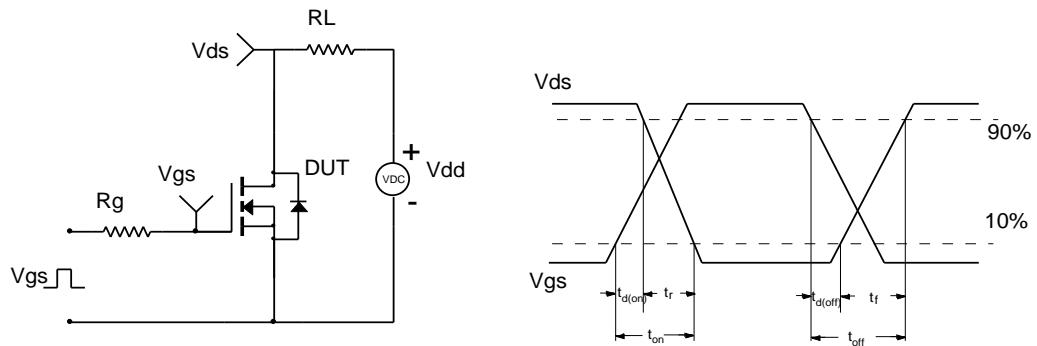


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

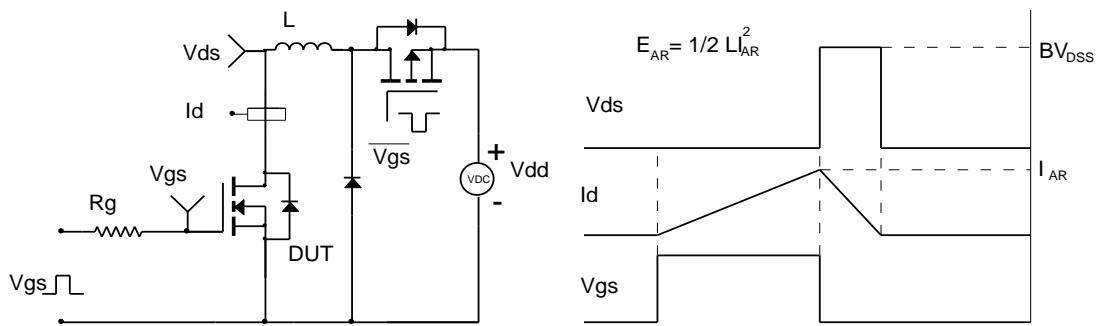
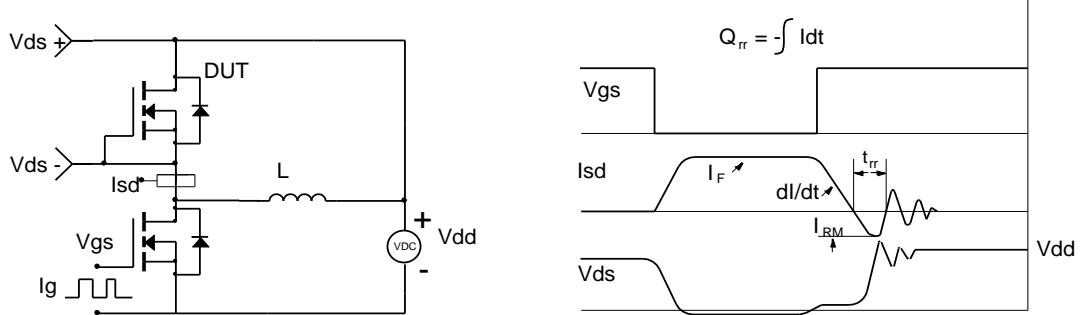


Figure D: Diode Recovery Test Circuit & Waveforms



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